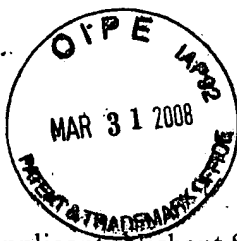


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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Nishant Sinha

Examiner: Walter Lee Lindsay Jr

Patent No.: 7,345,350

Group Art Unit: 2812

Issue Date: March 18, 2008

Docket No: 2002-0390.00/US

Title: PROCESS AND INTEGRATION SCHEME FOR FABRICATING CONDUCTIVE COMPONENTS,
THROUGH-VIAS AND SEMICONDUCTOR COMPONENTS INCLUDING CONDUCTIVE
THROUGH-WAFER VIAS

Certificate

APR 02 2008

of Correction

Commissioner for Patents
Office of Patent Publication
ATTN: Certificate of Correction Branch

We are transmitting herewith the attached:

- ☒ Authorization to charge the Certificate of Correction fee of \$100.00 to the Deposit Account No. 13-3092.
- ☒ Request for Certificate of Correction.
- ☒ Certificate of Correction Form - PTO-1050 (in duplicate)
- ☒ A return postcard.

Please charge any additional fees or credit overpayment to Deposit Account No. 13-3092.

Customer Number: 26809

Respectfully submitted,

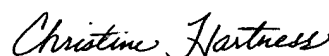
Date: March 28, 2008

By: 

Russ Slifer
Reg. No. 39,838

CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail, in an envelope addressed to: Commissioner of Patents and Trademarks, P.O. Box 1450, Alexandria VA 22313-1450, on this 28th day of March 2008.

Christine Hartness



Name

Signature

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IN UNITED STATES PATENT AND TRADEMARK OFFICE

Patent No.: 7,345,350

Docket No: 2002-0390.00/US

Issue Date: March 18, 2008

Patentee: Nishant Sinha



Title: **PROCESS AND INTEGRATION SCHEME FOR FABRICATING CONDUCTIVE COMPONENTS, THROUGH-VIAS AND SEMICONDUCTOR COMPONENTS INCLUDING CONDUCTIVE THROUGH-WAFER VIAS**

REQUEST FOR CERTIFICATION OF CORRECTION

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450
ATTN: Certificate of Correction Branch

It is requested that a Certificate of Correction be issued correcting printing errors appearing in the above-identified United States patent. Two copies of the text of the Certificate in the suggested form are enclosed.

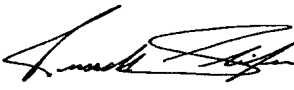
Pursuant to 1.20(a), the examiner is authorized to charge the Certificate of Correction fee of \$100.00 to the Deposit Account No. 13-3092.

Issuance of the Certificate of Correction would neither expand nor contract the scope of the claims as properly allowed, and re-examination is not required.

Respectfully submitted,

Customer Number: 26809

Date: March 28, 2008

By: 

Russ Slifer
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UNITED STATES PATENT AND TRADEMARK OFFICE CERTIFICATE OF CORRECTION

PATENT NO : 7,345,350

Page (1) of 1

DATED : March 18, 2008

INVENTOR(S) : Sinha

It is certified that error appear in the above-identified patent and that said Letters Patent is hereby corrected as shown below:

In column 13, lines 6-7, in Claim 3, delete "polysilicon, solder paste and a solder alloy." and insert - - polysilicon and solder paste. - -, therefor.

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UNITED STATES PATENT AND TRADEMARK OFFICE CERTIFICATE OF CORRECTION

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